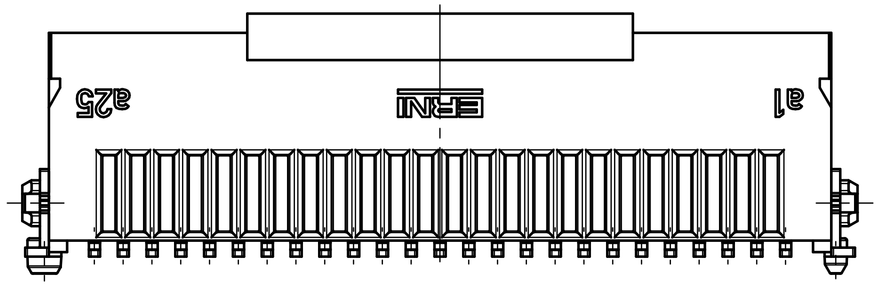
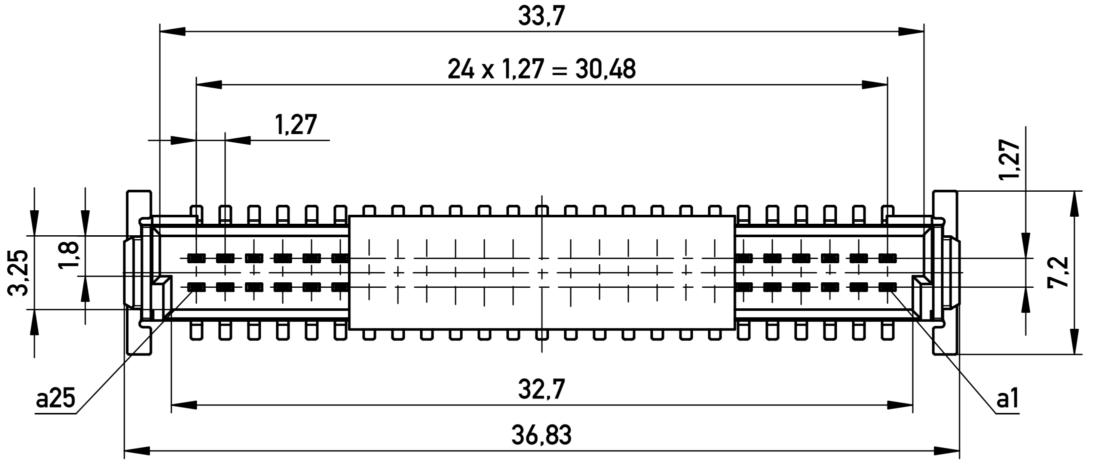
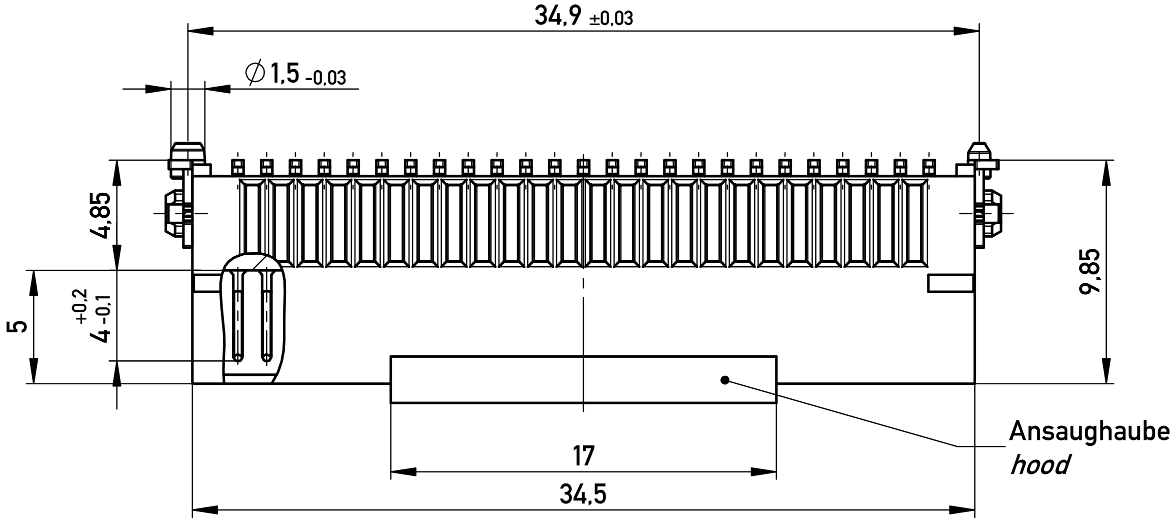
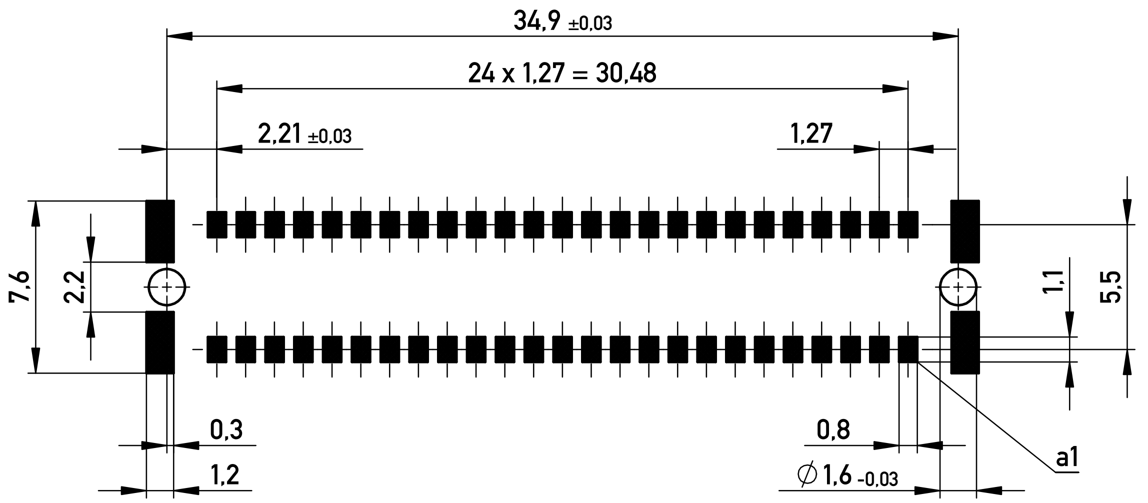






Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT

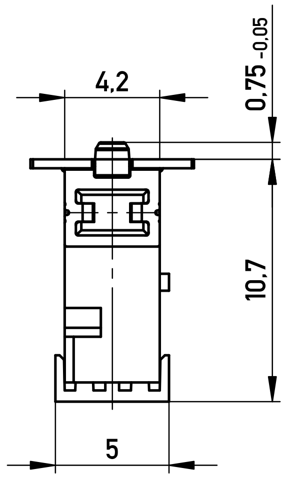


Anforderungsstufe 1
performance level 1

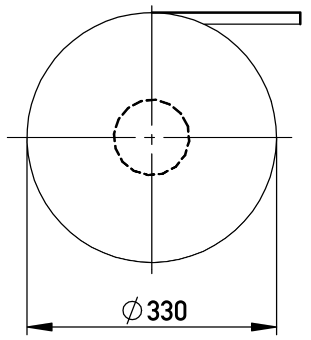
Kontaktbereich vergoldet
mating area gold plating

Anschlussbereich verzinnt 4-6 µm
terminal area 4-6 µm tin plating

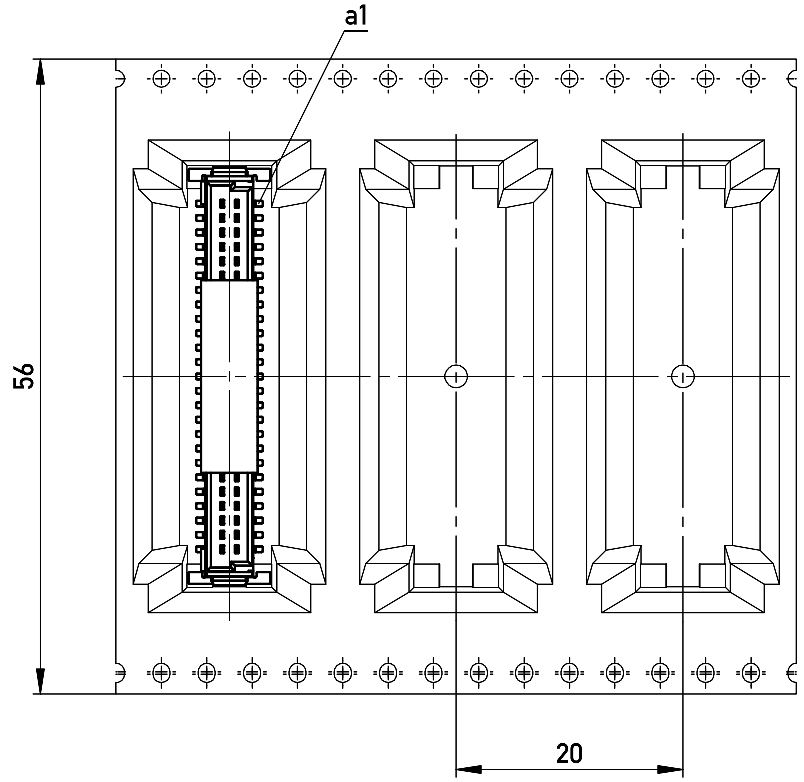
Koplanarität der Anschlüsse ≤ 0,1 mm
coplanarity area of termination ≤ 0,1 mm



Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
tape on reel packaging according to DIN IEC 60286-3
Verpackungseinheit: 250 Stück
packaging unit: 250 pcs



Abspulrichtung - *Reel off Direction*



BA 8-23 - hohe Bauhöhe
type 8-23 - High Profile

Information:

Tolerances
All Dimensions in mm

Scale 3:1

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To ensure that this is the latest version of this drawing, please contact one of the ERNI companies before using.

Subject to modification without prior notice.
Drawing will not be updated.

Designation
Messerl. SMC-Q 50-SMD-BA8-23
Male SMC-Q 50-SMD-type8-23

ERNI www.ERNI.com

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A3

Index	Date
f	07.09.2018

Class SMCQ